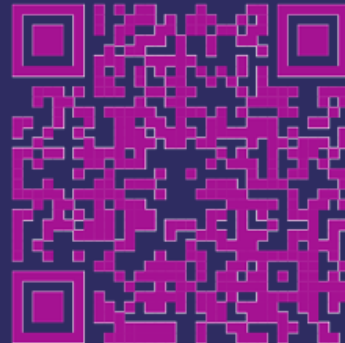


Horizon Europe – CHIPS-JU 2026

Kamran Choudhury - MIET
Innovate UK Business Connect
European Programmes
Digital (C4), Climate, Energy & Mobility (C5)



The UK's innovation agency



€53.8bn



Pillar 2

GLOBAL CHALLENGES &
EUROPEAN INDUSTRIAL
COMPETITIVENESS

Clusters

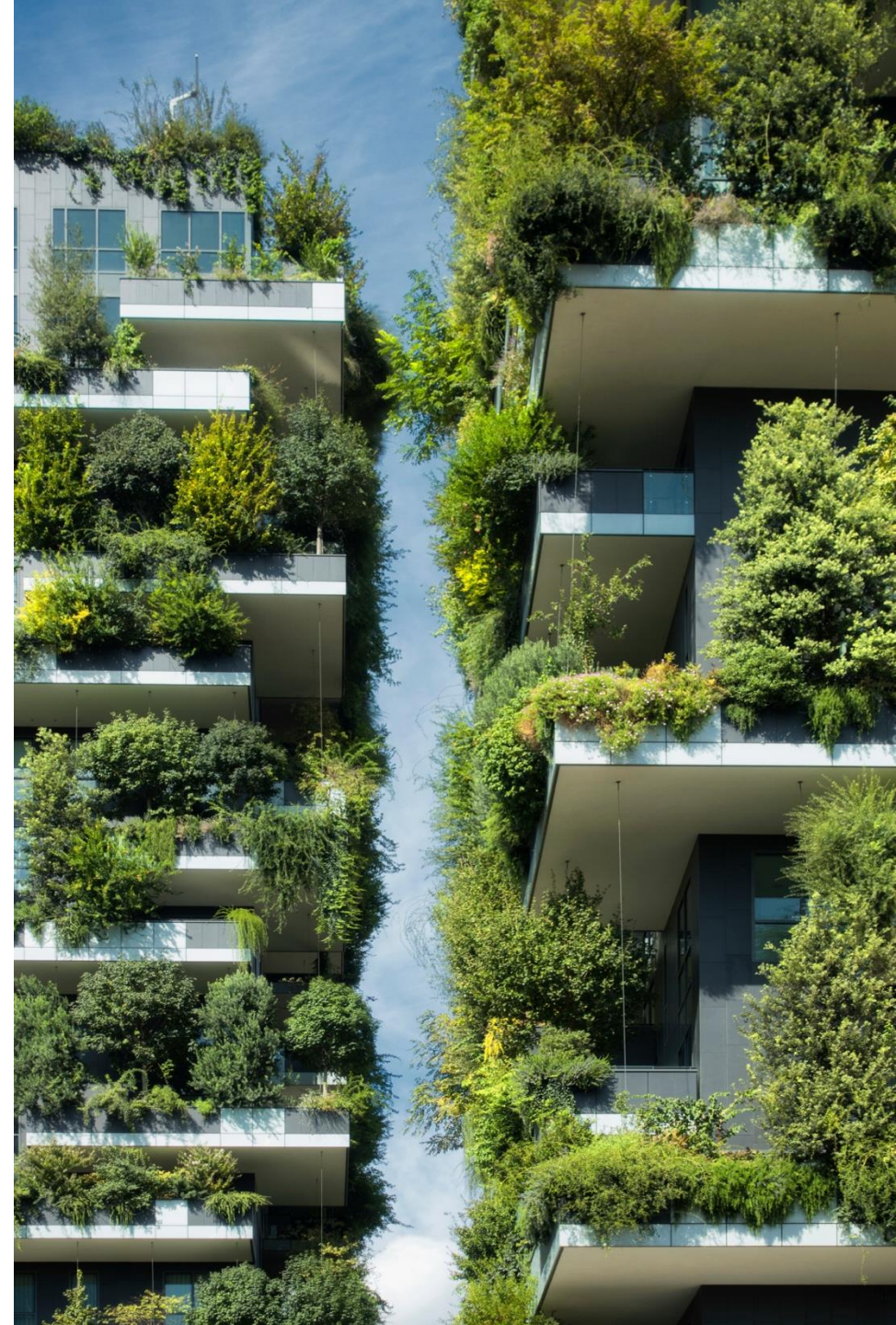
- Health
- Culture, Creativity and Inclusive Society
- Civil Security for Society
- Digital, Industry and Space
- Climate, Energy and Mobility
- Food, Bioeconomy, Natural Resources, Agriculture and Environment

AGENDA

1. Introductions
2. Horizon Europe UK CHIPS 2026 Scope & Eligibility
3. UK Semiconductor Landscape
4. Q&A

House Keeping

- **Microphone off** unless speaking please.
- Please post Q using the **Q&A FUNCTION**.
- Use the **Teams-Chat for connections**.
Save the Teams Chat – we will not be sharing this.
- Please message **Jo Byron** in the Teams chat if you are having technical issues.
- **The webinar is being recorded** and will be shared with the slides afterwards.



We are the UK's innovation agency

As part of UK Research and Innovation (UKRI), Innovate UK is publicly funded to drive innovation and productivity across the UK.

We work for you to create a better future by inspiring, involving and investing in businesses developing life-changing innovations.



UK Research
and Innovation



Innovate
UK

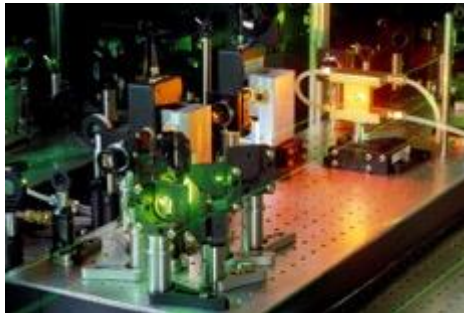
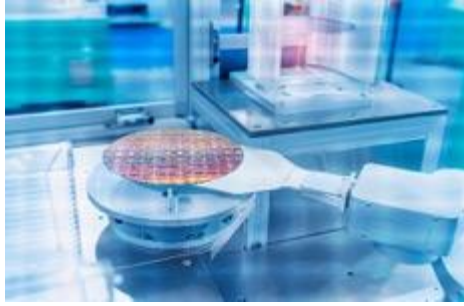


Innovate
UK

Chips JU – 2026 calls UK Scope & Eligibility

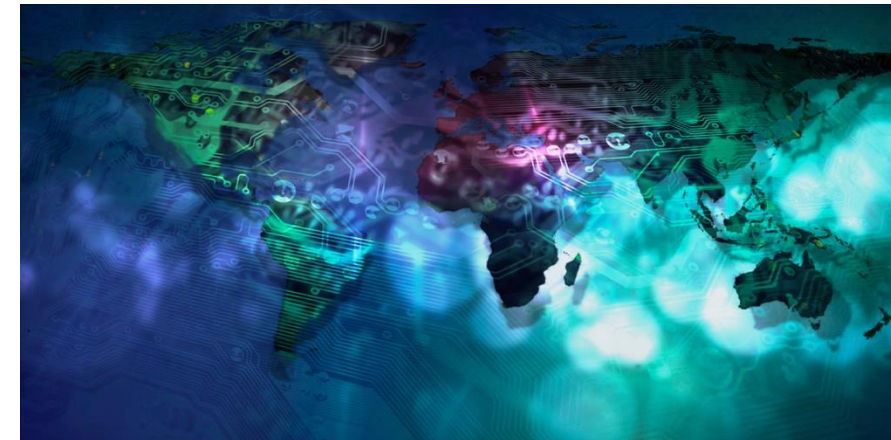
07th April 2026

Craig Sharp
National Contact Point - Digital



Outline

- Intros
- Chips Joint Undertaking (JU)
- 2026 Calls
- Previous projects / Key events



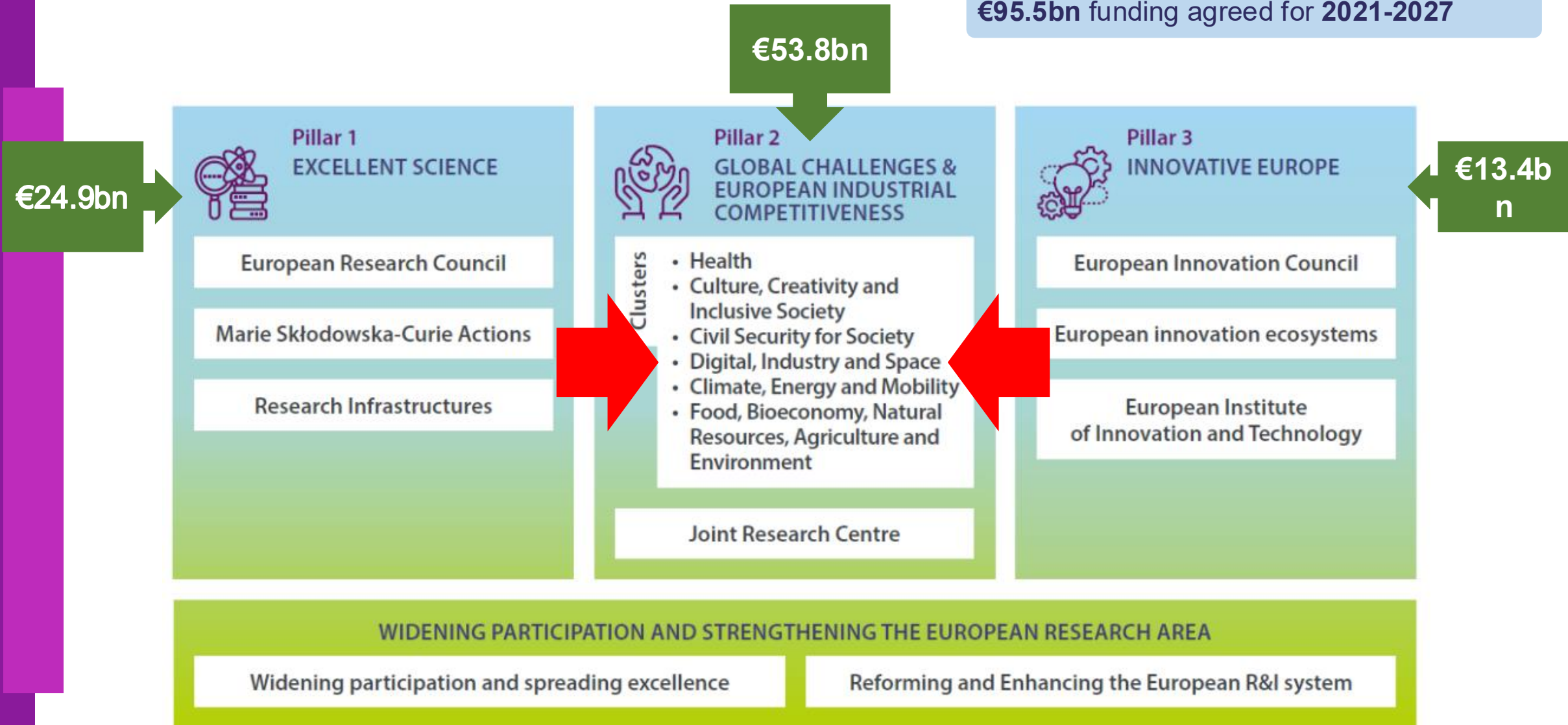
Support – National Contact Points

- National Contact Points are publicly funded and offer an accessible, free and confidential service for organisations interested participating in Horizon Europe. They provide impartial advice, tailored to each individual business and organisation – scope fit, help finding partners,
- Detailed knowledge of the Work Programme and how it aligns with the UK research and innovation priorities - www.ukri.org/HorizonEU
- UK National Contact Point list - <https://www.gov.uk/business-finance-support/horizon-europe-funding>
- [International NCP network](#) – support in Member States, Associated Countries and Third Countries
- Depth of understanding of European Commission processes including ‘non-standard’ issues such as JUs (some of the “partnerships”), EIC, ETPs, and other TLAs
- Help with navigating ‘[The \(Funding & Tenders\) Portal](#)’ – the EC publishes everything you could ever want to know, however, finding it can (occasionally) be a problem

If in doubt – ask your National Contact Point, their role is to support applicant organisations

Horizon Europe

€95.5bn funding agreed for 2021-2027



Budget figures exclude UK and other Associate Country contributions

Chips JU - General info (collaborative R&D)

- **Eligibility:** Must be a consortium of minimum 3 independent legal entities, each established in a different EU Member State (MS) or Associated countries, with at least 1 of them established in a MS.
- UK formally associated to Horizon Europe from 1/1/24 – so “2024” (and later) calls. Funded (and monitored) by EC, sign Grant Agreements, UK can coordinate

Award Criteria

- **Excellence**
- **Impact**
- **Quality** and **Efficiency** of implementation

Chips JU – non-initiative Main Types of Actions*

- **RIA** – Research and Innovation Actions – centre of gravity at **TRL 3-4**
- **IA** – Innovation Actions – centre of gravity at the **TRL 5-8**
- **CSA** – *Coordination and Support Actions*

The Horizon Europe funding rates in this presentation are specific to Chips JU calls

Chips JU

A one-of-a-kind Partnership for Europe's Chips Industry

- Chips JU is a tri-partite public-private partnership, established in 2023, as a successor to Key Digital Technologies JU (KDT JU) to advance nano-electronic chip technologies in Europe
- Funded by the European Union, Participating States, and Private Members

CHIPS JU TRI-PARTITE STRUCTURE



Private Members
Industry Associations



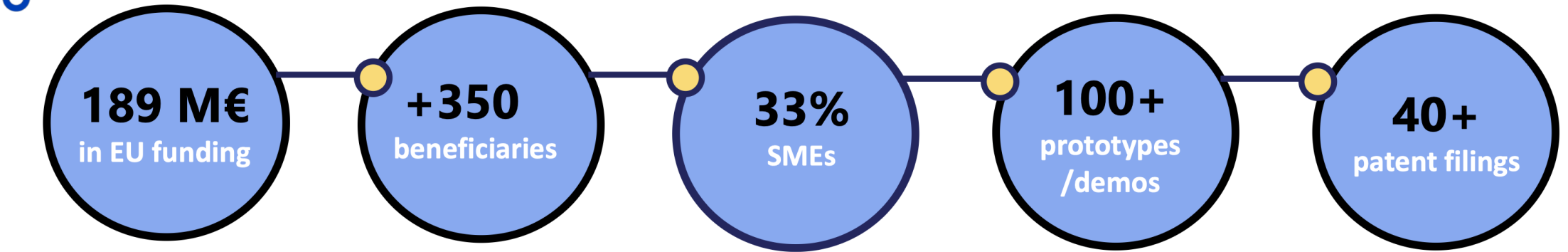
European Union
European Commission



Public Authorities
Participating States

Last year (2025)

ECS R&D Programme: 2025 Results



Projects cover critical domains like **EV power electronics, AI chips, manufacturing 4.0,** and more, feeding directly into Europe's chip supply chain with new capabilities.

Chips Joint Undertaking (JU)

- 2 funding call streams –
 - Electronics Components & Systems (ECS) - €1.3Bn programme budget - 30-50% of ECS budget in open topics (roadmap), rest in focused topics
 - Chips for Europe initiative €1.4Bn planned budget (Chips for Europe initiative – UK eligible for the Horizon Europe funded topics)
- More info/funded projects: <https://www.chips-ju.europa.eu/Projects/>
- Annual calls published - mix of 1 and 2-stage calls
- Co funding mechanism – Chips JU and National Funding Authorities (UK joined March 2024)
- Up to £10m UK co-funding for 2026 Chips JU call (through IUK)
- Chips JU 2026 calls published ([QR code for 2026 ECS call](#))



Chips JU 2026 Electronic Components & Systems (ECS) topics

Topic Identifier	Topic title	Type of Action	Chips JU Topic Budget*	Projects	Deadlines
HORIZON-JU-Chips-2026-IA	Global call according to ECS SRIA 2026 (IA)	IA	€40m*	tbc	7/5/26, 17/9/26
HORIZON-JU-Chips-2026-FT1	Resilience call reinforcing Europe's strength in power electronics	IA	€20m*	2	17/9/26
HORIZON-JU-Chips-2026-FT2	Resilience call reinforcing Europe's strength in photonics	IA	€20m*	2	17/9/26
HORIZON-JU-Chips-2026-FT3	Resilience call reinforcing Europe's strength in health	IA	€20m*	1	17/9/26
HORIZON-JU-Chips-2026-1-RIA	Global call according to ECS SRIA 2026 (RIA)	RIA	€50m*	tbc	7/5/26, 17/9/26
HORIZON-JU-Chips-2026-2-RIA	RIA Resilience call on the 6G Front End Module	RIA	20m*	1	17/9/26
<i>HORIZON-JU-Chips-2026-3-RIA</i>	<i>Call with Digital Partnership and TTC countries</i>	<i>RIA</i>	<i>5m</i>	<i>2</i>	<i>17/9/26</i>
<i>HORIZON-JU-Chips-2026-CSA</i>	<i>Supply chain resilience (CSA)</i>	<i>CSA</i>	<i>2m</i>	<i>1</i>	<i>17/9/26</i>

* plus co-funding from national funding agencies

Global calls – ECS Strategic Roadmap

- The Global RIA and IA topics both refer to the ECS SRIA (roadmap) (2026)
- List of SRIA sub-heading areas that are in scope (in SRIA) in each of the Global topics (RIA and IA)
- <https://ecssria.eu/2026>

Excerpt from sub-headings – link to full SRIA roadmap

This topic is the IA-part of the bottom-up programming. The topic will be open to the following major challenges:

Topics and Major Challenges	Open/ Closed
1.1 - Process technology, equipment, materials and manufacturing	
Major Challenge 1: Advanced computing, memory and in-memory computing concepts	Open
Major Challenge 2: Novel devices and circuits that enable advanced functionality	Open
Major Challenge 3: Advanced heterogeneous integration and packaging solutions	Open
Major Challenge 4: World-leading and sustainable semiconductor manufacturing equipment and technologies	Open
1.2 - Components, modules and systems integration	
Major Challenge 1: Enabling new functionalities in components with More-than-Moore technologies.	Open
Major Challenge 2: Integration technologies, processes and manufacturing.	Open
Major Challenge 3: Sustainability	Open
1.3 - Embedded software and beyond	
Major Challenge 1: Efficient engineering of embedded software	Open
Major Challenge 2: Continuous integration and deployment	Open

Major Challenge 3: Lifecycle management	Open
Major Challenge 4: Embedding data analytics and Artificial Intelligence	Open
Major Challenge 5: Support for Sustainability by embedded software	Open
Major Challenge 6: Software reliability and trust	Open
Major Challenge 7: Hardware virtualization for efficient SW engineering	Open
1.4 - System of Systems	
Major Challenge 1: SoS architecture and open integration platforms	Open
Major challenge 2: SoS interoperability	Open
Major Challenge 3: Evolvability of SoS composed of embedded and cyber-physical systems	Open
Major Challenge 4: SoS integration along the life cycle	Open
Major Challenge 5: Control in SoS composed of embedded and cyber-physical systems	Open
Major Challenge 6: SoS monitoring and management	Open
2.1 - Edge Computing and Embedded Artificial Intelligence	
Major Challenge 1: Increasing the energy efficiency	Open
Major Challenge 2: Managing the increasing complexity of systems	Open
Major Challenge 3: Supporting the increasing lifespan of devices and systems	Open
Major Challenge 4: Ensuring European sustainability in AI	Open

IA Resilience Call FT1 - Reinforcing Europe's Strength in Power Electronics

€20m Chips JU budget*, 2 projects

Cross innovations fields focusing on crucial topics should address one or more of the several domains:

- WBG substrates to reduce EU dependency on material and provide more sustainable, industrially compatible solutions.
- WBG platform for cost effectiveness, available in 300mm for GaN and/or SiC to improve yield and power density and close gaps in the value chain.
- A toolbox (e.g. wafer cut, smart stacking, thin layer transfer, epitaxy, UWBG materials) for further innovation schemes.
- Next generation or optimised new power semiconductor devices fitting their application.
- Adding intelligence to power semiconductor devices on control and/or sensor side.
- Facilitate the propagation of EU Packaging/Integration excellence along the entire value chain
- Explore use of heterogeneous and functional integration for improved performance, reliability, robustness, cost competitiveness
- Advanced characterization techniques for new materials, devices, and systems.
- Implement AI at system level and/or make use of AI methods to increase innovation speed

*National Funding in addition to Chips JU budget for this topic

www.ukri.org/HorizonEU

IA Resilience Call FT2 - Reinforcing Europe's Strength in Photonics

€20m Chips JU budget*, 2 projects

Proposals are expected to address several of the following elements:

- Scaling of wafer-level photonic processes for key materials (e.g. SiN, InP , GaAs)
- Development of packaging and test solutions compatible with co-packaged optics and advanced photonic-electronic integration.
- Integration of heterogeneous materials and components, using advanced packaging and assembly approaches.
- Design-process-equipment co-optimisation, enabling repeatable, cost-effective production of complex photonic circuits and systems, including use of PDKs and validated building blocks.
- Demonstration of system-level functionality through application-relevant use cases in strategic sectors (e.g. AI, sensing, telecommunication, mobility, health), with quantified performance metrics and clear market relevance.

* National Funding in addition to Chips JU budget for this topic

IA Resilience Call FT3 - Reinforcing Europe's Strength in Health

€20m Chips JU budget*, 1 project

Proposals are expected to address integrated technologies for monitoring, imaging and biomedical research:

- Advanced wearable health technologies and integrated solutions
- Personalized imaging technologies
- Advanced laboratory and scientific solutions
- Key digital technologies enabling digital healthcare transformation
- Edge-to-cloud architectures enabling distributed data processing and decision-making across the healthcare continuum.
- Embedded and edge intelligence, real-time analysis, adaptive system behaviour closer to point of care.
- Robust data protection frameworks ensuring patient privacy and compliance with healthcare regulations.
- Interoperable platforms and interfaces to support seamless integration across devices, systems, and care settings.
- AI-driven methods and tools for diagnostics, monitoring, prediction, and clinical decision support.
- Automation and autonomous systems, including robotics, to enhance operational efficiency and assist care delivery.

* National Funding in addition to Chips JU budget for this topic

www.ukri.org/HorizonEU



RIA Resilience Call FT1 – Call on the 6G Front End Module

€20m Chips JU budget*, 1 project

Proposals submitted should address the following set of FEM constituent technologies in priority including challenges issues such as:

- Transmitter and Power amplification
- Receiver: Very low noise and high dynamic range in receivers
- Filters
- TRX
- Integration/packaging
- Sustainability: Thermal modelling/optimisation of chips modules; energy efficient designs
- Advanced Antenna System
- ISAC: technology for ISAC native waveforms, and showcasing practical ISAC

* National Funding in addition to Chips JU budget for this topic

ECS International collaboration - Call with Digital Partnership and TTC countries

€5m Chips JU Budget, 2 projects (€2-2.5m each)

The scope includes, but is not limited to, the following:

- Address research reaching TRL 4 with high potential not yet demonstrated in the design, fabrication process and/or packaging segments of the micro-nano-electronics and integration technologies value chain.
- Focus innovation on materials, physical concepts or device architecture building on neuromorphic or integration technologies.
- Provide a projection of the expected gains and main figures of merit of the proposed approaches.
- Multi-disciplinary research activities should address part of the semiconductor value chain from materials, processes, equipment, metrology, back-end processing to packaging, integration and tests.

Chips JU 2026 Chips for Europe (CfE) topics (Horizon Europe)

Topic Identifier	Topic title	Type of Action	Topic Budget	No of projects	Deadline
<i>HORIZON-JU-CHIPS-2026-QUANTUM-1</i>	<i>Quantum Chips Design: Driving Europe's Quantum Design Ecosystem and Enabling Quantum Design Tools Innovation</i>	<i>RIA</i>	<i>30m*</i>	<i>1</i>	<i>17/9/26</i>
HORIZON-JU-CHIPS-2026-QUANTUM-2	Quantum Chips: Enabling Technologies	RIA	20m*	3-4	17/9/26

* plus co-funding from national funding agencies

Chips for Europe 2026 topics

www.ukri.org/HorizonEU



Quantum Chips: Enabling Technologies and Design

€20m RIA topic budget*, 3-4 projects.

- Focus on enabling technologies that support, control, and read out quantum systems without funding the core quantum chips
- Target system-level integration and interfaces and validate solutions in relevant environments, preferably via EU pilot lines/MPWs
- Solutions may include for example:
 - Control and readout electronics across temperature stages including cryogenic
 - Photonic/optical components for routing, modulation, detection and timing
 - Transduction and networking technologies such as microwave-optical conversion
 - Cryogenics, interconnects, packaging and heterogeneous integration for modular assemblies
- Two complementary categories of enabling technologies covered: Process Enabling Technologies, and Operations Enabling Technologies.
- Supports enabling subsystems up to pilot-line validation / MPW tape-out where relevant, in alignment with Chips JU pilot-line access

Access – EU, EEA, UK, CH, Canada, RoK, NZ, Israel

* National Funding in addition to Chips JU budget for this topic

www.ukri.org/HorizonEU

UK co-funding Key Conditions

- We have allocated up to £10m to co-fund UK partners within Chips JU projects in this 2026 call.
- All types of UK registered organisations can apply for funding.
- Your project:
 - Must be collaborative
 - must contain at least one UK registered business of any size
 - be or involve at least one UK registered [micro, small or medium sized enterprise](#) (SME)
 - University/RTO costs can be up to a maximum of 30% of the total UK eligible costs in a proposal
- If your total grant is greater than £750,000, then you must get in touch with us by email as soon as possible before you start your application and at least 10 working days before the competition closes, where we will decide whether to approve your request.
- [Further guidance](#) available on our Funding rules page.
- All UK participants are advised to contact the Innovate UK contact point before committing to participate in any proposal.

2026 Chips ECS topics – UK co-funding rates

Co-Funding rates from Innovate UK in the 2026 Chips JU Horizon Europe co-funded ECS calls are:

Action	Large	Medium	Small	RTO/Uni
IA calls	50%-JU%	60%-JU%	70%-JU%	100%-JU%
RIA calls	50%-JU%	60%-JU%	70%-JU%	100%-JU%

UK Funding - additional information

- UK registered research organisations in your consortium can share up to 30% of the UK total eligible project costs. If your consortium contains more than one UK research organisation, this maximum will be shared between them.
- Of that 30% you could get funding for your eligible project costs of up to: 80% of full economic costs (FEC) if you are a Je-s registered institution such as an academic
- Subcontractors are allowed in this competition but they must not account for more than 20% of the UK partners' total eligible costs.

In the event that the UK receives more successfully approved projects from Chips JU, then Innovate UK reserves the right to take a portfolio approach.

Consortium building

Chips – annual events - [EF ECS](#) (Dec), [ECS brokerage](#) (Feb), [ECS Collaboration Tool](#) (also used for Eureka Xecs-free login required), PICSummit (Nov)

Previous funded projects: (*quantum* –see also *Quantum Flagship* <https://qt.eu>)

Chips JU – previous projects – CORDIS <https://cordis.europa.eu/search> :

Chips JU funded projects details through Horizon Europe and Horizon 2020 “ECSEL” – using filters allows you to see past projects and participants, includes ability to contact them – search by area, topic, project, FP (Horizon Europe, H2020, etc), countries, Filter for keywords, countries, year, etc..

Contacts - and contacts of contacts... networking, events (including UK Universities and Research Organisations experienced in European funding)

No single mechanism..

Funded project/partner info

(EC CORDIS database – projects, participants)

<https://cordis.europa.eu/search>

Filter by

✕
🔍

CONTENT

- Collection (1) +
- Domain of Application +
- Language (1) +
- Programme (2) +
- Last updated +

PROJECT

- Acronym / ID +
- Field of Science (EuroSciVoc) +
- Start/End date +
- Total cost +
- EU contribution +
- Call ID (3) +
- Topic ID +

ORGANISATION

- Name +
- Country / Territory (2) +
- Region +

✕ Clear all filters

- 🔖 Save search ▾
- 🔖 My saved searches ▾
- 📄 Download search results ▾
- 📡 RSS feed

Include archived content ⓘ 🔗 Expert search

Active filters: 9 ▾

65 results for 'semiconductor' 📅 Last update ⬆️ ⬆️ Title ⬆️

HORIZON 2020

PROJECT

UltimateGaN Research for GaN technologies, devices, packages and applications to address the challenges of the future GaN roadmap

ID: 826392

From: 1 May 2019 to: 31 October 2022

The main objective of UltimateGaN is to safeguard Europe's leading position in terms of power semiconductors and high performance RF applications by driving an innovative breakthrough change with the next generation of GaN-technologies. Several precedes...

Coordinated in: Austria

Programme: [ECSEL](#), [INDUSTRIAL LEADERSHIP - Leadership in enabling and industrial technologies - Information and Communication Technologies \(ICT\)](#)

Last update: 1 September 2025 🔖 Add to my booklet

HORIZON 2020

PROJECT

PowerBase Enhanced substrates and GaN pilot lines enabling compact power applications

ID: 662133

From: 1 May 2015 to: 30 June 2018

The key objective of PowerBase "Enhanced substrates and GaN pilot lines enabling compact power applications" is to ensure the availability of Electronic Components and Systems (ECS) for key markets and for addressing societal challenges, aiming at keep...

Coordinated in: Austria

Programme: [ECSEL](#), [INDUSTRIAL LEADERSHIP - Leadership in enabling and industrial technologies - Information and Communication Technologies \(ICT\)](#)

Last update: 14 September 2023 🔖 Add to my booklet

HORIZON 2020

PROJECT

Power2Power The next-generation silicon-based power solutions in mobility, industry and grid for sustainable decarbonisation in the next decade.

ID: 826417

From: 1 June 2019 to: 30 September 2022

The objectives in Power2Power aim to foster a holistic, digitized pilot line approach by accelerating the transition of ideas to innovations in the Power Electronic Components and Systems domain. In the course of this project, the international leadership of the...

Coordinated in: Germany

Programme: [ECSEL](#), [INDUSTRIAL LEADERSHIP - Leadership in enabling and industrial technologies - Information and Communication Technologies \(ICT\)](#)

Last update: 11 December 2023 🔖 Add to my booklet

HORIZON 2020

PROJECT

WAYTOGO FAST Which Architecture Yields Two Other Generations Of Fully depleted Advanced Substrate and Technologies

ID: 662175

From: 1 May 2015 to: 31 December 2017

The proposed pilot line project WAYTOGO FAST objective is to leverage Europe leadership in Fully Depleted Silicon on Insulator technology (FDSOI) so as to compete in leading edge technology at node 14nm and beyond preparing as well the following nod...

Coordinated in: France

Programme: [ECSEL](#), [INDUSTRIAL LEADERSHIP - Leadership in enabling and industrial technologies - Information and Communication Technologies \(ICT\)](#)

Last update: 10 March 2023 🔖 Add to my booklet

HORIZON 2020

PROJECT

IT2 IC Technology for the 2nm Node

ID: 875999

Coordinator

INFINEON TECHNOLOGIES AG

Address
AM CAMPEON 1-15
85579 Neubiberg
🇩🇪 Germany 📍

Region
Bayern > Oberbayern > München, Landkreis

Activity type
Private for-profit entities (excluding Higher or Secondary Education Establishments)

Links
[Contact the organisation](#) [Website](#)
[Participation in EU R&I programmes](#)
[HORIZON collaboration network](#)

Net EU contribution ⓘ
€ 1 675 008,00

Total cost ⓘ
€ 8 375 040,00

Participants (60)

Sort alphabetically ⬆️	Sort by Net EU contribution ⬆️	Expand all
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">ABB OY</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇫🇮 Finland</div>	Net EU contribution ⓘ € 480 425,00	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">FAGOR AUTOMATION S COOP</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇪🇸 Spain</div>	Net EU contribution ⓘ € 206 250,00	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">INGETEAM POWER TECHNOLOGY SA</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇪🇸 Spain</div>	Net EU contribution ⓘ € 281 600,00	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">THIRD-PARTY ⓘ</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">INGETEAM RESEARCH INSTITUTE SOCIEDAD LIMITADA</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇪🇸 Spain</div>	Net EU contribution ⓘ € 19 427,63	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">AGENCIA ESTATAL CONSEJO SUPERIOR DE INVESTIGACIONES CIENTIFICAS</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇪🇸 Spain</div>	Net EU contribution ⓘ € 226 012,50	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">FRAUNHOFER GESELLSCHAFT ZUR FORDERUNG DER ANGEWANDTEN FORSCHUNG EV</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇩🇪 Germany</div>	Net EU contribution ⓘ € 335 891,50	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">TECHNISCHE UNIVERSITEIT DELFT</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇳🇱 Netherlands</div>	Net EU contribution ⓘ € 653 462,25	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">OSTBAYERISCHE TECHNISCHE HOCHSCHULEAMBERG-WEIDEN</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇩🇪 Germany</div>	Net EU contribution ⓘ € 271 250,00	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">RISE RESEARCH INSTITUTES OF SWEDEN AB</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇸🇪 Sweden</div>	Net EU contribution ⓘ € 298 812,50	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">TECHNISCHE UNIVERSITAT DORTMUND</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇩🇪 Germany</div>	Net EU contribution ⓘ € 245 000,00	▾
<div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">INTERUNIVERSITAIR MICRO-ELECTRONICA CENTRUM</div> <div style="background-color: #ccc; padding: 5px; margin-bottom: 5px;">🇧🇪 Belgium</div>	Net EU contribution ⓘ € 201 435,94	▾

Contact organisation option

Links/further information

- Chips JU open calls – note the ECS and Chips for Europe call documents are updated from time to time – open calls are at <https://www.chips-ju.europa.eu/Participate/>
- [European Commission Funding Tenders Portal link to Chips JU topics](#)
- [ECS Roadmap for the Global topics - ECS SRIA 2026](#) (~600p) – the 2 (RIA and IA) Global topics also contain 4+ pages of SRIA subheadings corresponding to the ECS SRIA
- [ECS collaboration tool](#) (need to register) – recent project ideas, requests posted – filter by ECS 2026

Brokerage/networking events

- Chips JU – [EF ECS](#) (Dec) and ECS brokerage event* (Feb)
- Also – [PIC Summit Europe](#) (NL)
- [CORDIS](#) & Chips JU [project databases](#) (funded project and participant lists)



2026 ECS calls pdf

www.ukri.org/HorizonEU



2026 C4E calls pdf



UK Research
and Innovation

Thank you

Horizon Europe - Digital NCP

Craig Sharp - Digital NCP-Digital@iuk.ukri.org

Newsletter Subscription: <https://eufunding.ukri.org/subscribe>

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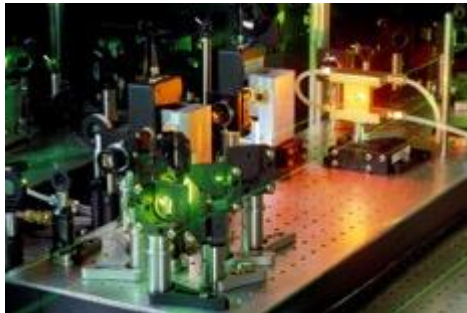
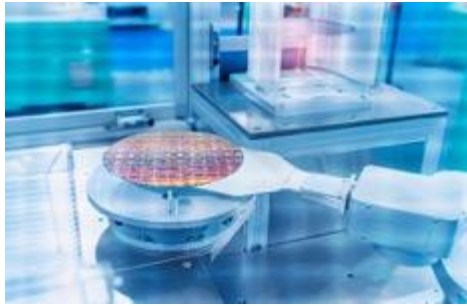


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The UK Semiconductor Landscape & Innovate UK Opportunities

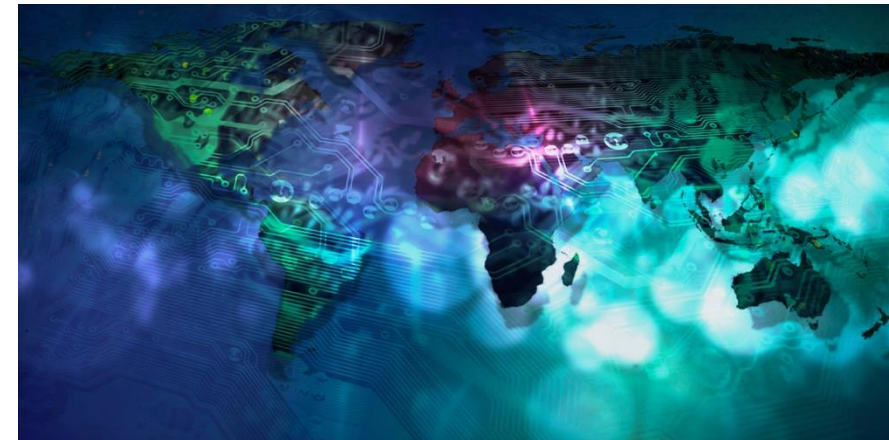
Dr Iain S. Mauchline
Head of Semiconductors

07th April 2026



Outline

- Who are UKRI, Innovate UK & EPSRC
- UK Semiconductor Landscape



Who are Innovate UK and EPSRC within UKRI?

- We are the UK's Research & Innovation agency
- A key delivery body of HMG's R&I policies and strategies
- We support academic research and business-led innovation in all sectors, technologies and UK regions
- [IUK New Approach Prospectus](#)

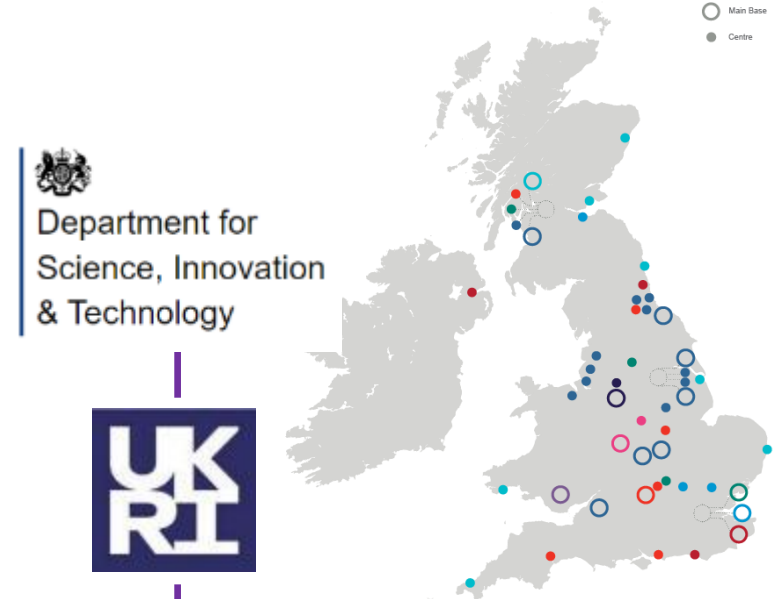
Innovate UK mission

To help UK businesses grow through the development and commercialisation of new products, processes, and services, supported by an outstanding innovation ecosystem that is agile, inclusive, and easy to navigate



EPSRC mission

To support new ideas and transformative technologies which are the foundations of innovations that improve our economy, environment and society, by investing in world-leading research and skills



UK Industrial Strategy - Digital and Technologies

The UK's Modern Industrial Strategy backs 8 Sectors each of which has a Sector Plan

- Advanced Manufacturing, Clean Energy Industries, Creative Industries, Defence, Digital and Technologies, Financial Services, Life Sciences, and Professional & Business Services

The Industrial Strategy: Digital and Technologies Sector Plan emphasises the importance of semiconductors as ***one of the “frontier technologies”***, that have been **identified as critical** to the UK's future resilience, economic prosperity and national security.

“We will prioritise frontier technologies with the greatest growth potential”

What are the Frontier Technologies?

- *ACT (Advanced Connective Technologies - fka Future Telecommunications)*
- *AI*
- *Cyber Security*
- *Engineering Biology*
- *Quantum Technologies*
- *Semiconductors*

UK Semiconductors - Recently Announced Investments

- Establishing a new UK Semiconductor Centre (up to £19 million)
- Funding Innovation and Knowledge Centres (IKCs) in Neuromorphic Computing Hardware and Heterogeneous Integration joining existing IKCs in Photonics and Power Electronics
- Boosting the UK's chip design capability through a new Chip Design Enablement Programme (up to £5 million)
- Improving the semiconductor talent pipeline through a £35 million UK-wide skills programme ([STEP](#))
- A new Centre for Doctoral Training in Future Semiconductor Skills





Mobilising the UK Semiconductor Centre

- Building a world-class UK semiconductor ecosystem that drives scale-up, attracts global investment and partnerships to fuel growth

Missions & Outcomes

ECOSYSTEM & ADVOCACY



We will have a more connected and visible UK innovation ecosystem

STRATEGY & ROADMAP



We will have an aligned strategy including a long-term roadmap guiding investment

SCALE-UP



We will have accelerated the scale-up and growth of UK semiconductor companies

INTERNATIONAL



We will have stronger global partnerships and greater inward investment

WORKFORCE



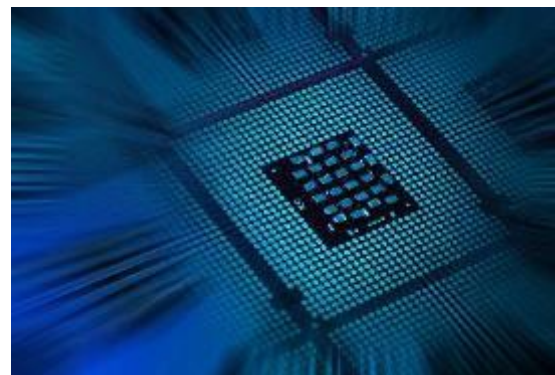
We will have developed the skilled workforce the sector needs

What are the UK Strengths?



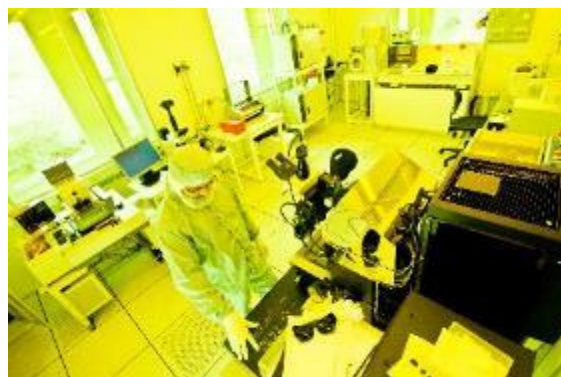
Research Strength

- Photonics / photonic systems integration
- Integrated circuit design
- Compound semiconductors
- Embedded security, on chip
- Polymer electronic materials
- New and advanced materials



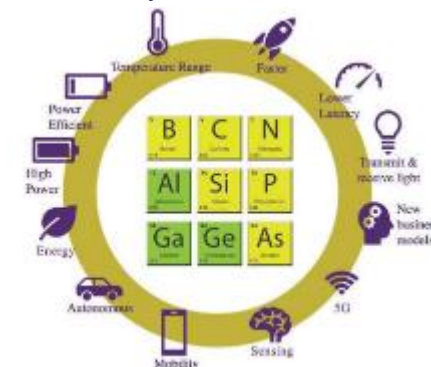
Compound, Advanced Materials, Advanced Packaging

- Strengths across the UK, including South Wales, Scotland, NE England, Cambridge, SW England
- World leading advanced materials companies
- uWBG – GaN, SiC, Ga₂O₃
- Photonics, PICs, Co-Packaging
- Heterogeneous/Hybrid



Semiconductor Design/IP

- Over 100 semiconductor design/IP companies,
- Global companies in IP, AI, SoCs, IoT, graphics
- World leading chip-design sector with clusters including Cambridge, Bristol and Edinburgh



Semiconductor research & innovation capabilities

• [Future Photonics Hub](#)



• [National Epitaxy Facility](#)



• [Future Compound Semiconductor Manufacturing Hub](#)



• [Royce Institute](#) - Advanced Materials



• [REWIRE IKC](#) - Wideband Gap Semiconductors



• [C-PIC IKC](#) - Silicon Photonics



• [CHIMES IKC](#) – Heterogeneous Integration



• [NEUROWARE IKC](#) - Neuromorphic computing hardware

• [NMIS](#), [ANZIC](#), [NASPIC](#) - Manf, NZ, AdvPack

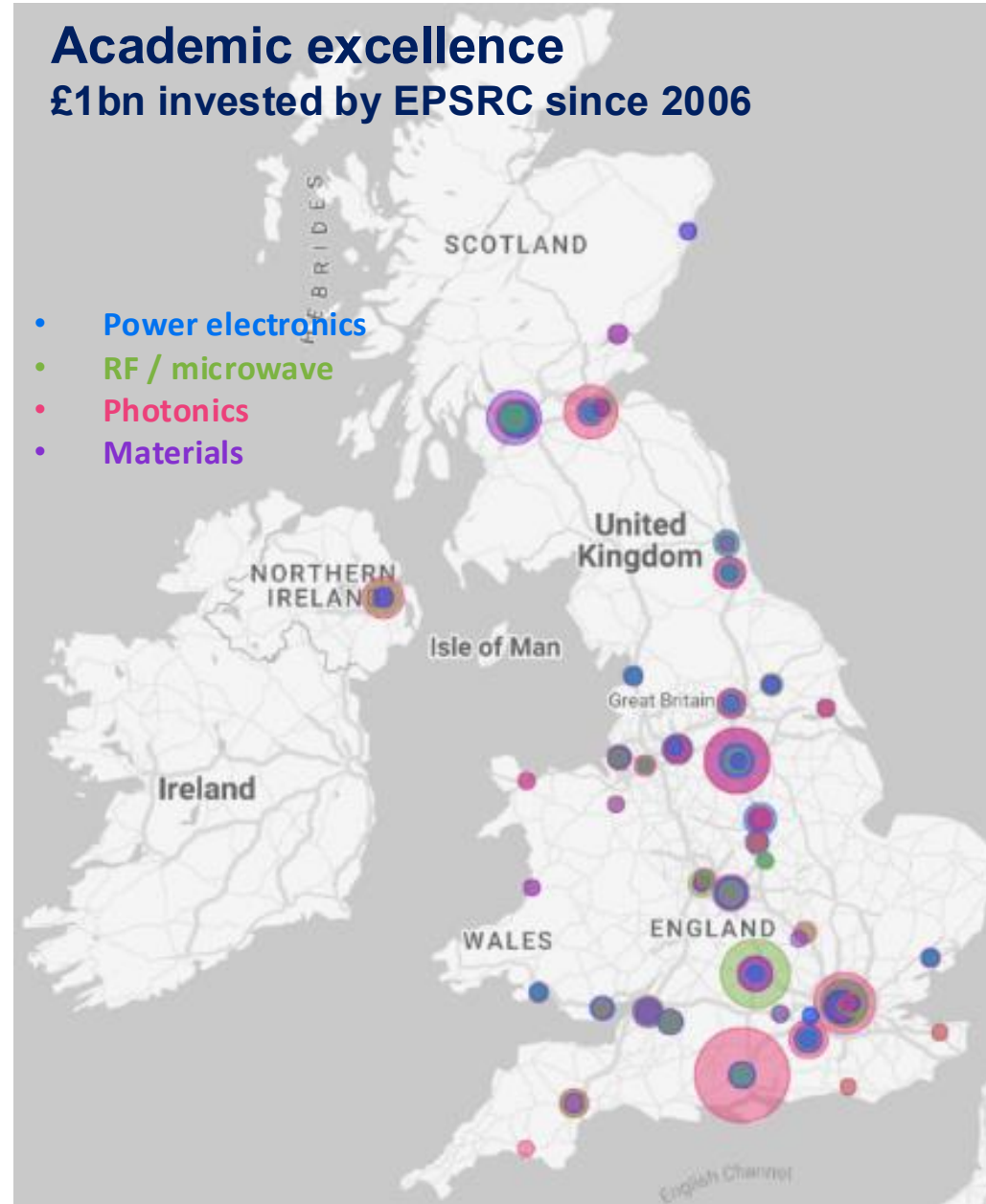


• [eFutures](#) - Academic Network for electronics



Academic excellence
£1bn invested by EPSRC since 2006

- Power electronics
- RF / microwave
- Photonics
- Materials



Semiconductor- Stakeholders

Government



Trade



UK Semiconductors – Related Funding Calls

- **Frontier AI Discovery** : UK registered organisations can apply for a share of up to £2.5 million to develop feasibility studies for frontier AI and foundation models. This funding is from Innovate UK.
 - **Competition opens:** Tuesday 14 April 2026, **Competition closes:** Wednesday 10 June 2026 11:00am
- **AI Champions: Frontier AI Phase 1**: UK registered SME businesses can apply for a share of up to £3 million to deliver feasibility studies for frontier artificial intelligence (AI), and machine learning (ML) technologies with a clear route defensible scale-up. This is funded by Innovate UK.
 - **Competition opens:** Tuesday 17 March 2026, **Competition closes:** Wednesday 29 April 2026 11:00am
- **Cfi: Advanced Connectivity Technologies (ACT) – Call 1**: UK registered organisations can apply for a share of £15 million, including VAT, to develop near term, testable solutions that advance the UK’s Secure & Resilient and Sustainable Network Grand Challenges through deployable prototypes on UK testbeds.
 - **Competition opens:** Wednesday 1 April 2026, **Competition closes:** Wednesday 3 June 2026 11:00am
- **Solution Development for Advanced Connectivity Technologies**: UK registered organisations can apply for a share of up to £25 million to develop secure, sustainable or sovereign connectivity technologies that support the UK’s Advanced Connectivity Technologies programme. This funding is from DSIT.
 - **Competition opens:** 01 April 2026, **Competition closes:** Wednesday 13 May 2026 11:00am
- **Horizon Europe 2026-27: Digital, Industry and Space (Cluster 4)**: Topics available under Horizon Europe's Cluster 4 programme for 2026-27, with a total budget of €1.5bn
 - **Competition opens:** December 2025, **Competition closes:** Various – March 2026 to September 2027
- **Contracts for Innovation: ProQure - Scaling UK Quantum Computing**: Organisations can apply for up to £14 million in phase 1 to develop, build and validate integrated quantum computing hardware and software to demonstrate commercial scale deployment and applications of your quantum computing solution.
 - **Competition opens:** Friday 27 March 2026, **Competition closes:** Friday 29 May 2026 11:00am
- **UK-Germany Collaborative Innovation for Quantum Technologies 2026**: UK registered organisations can apply for a share of up to £3 million for innovative projects in quantum.
 - **Competition opens:** Thursday 12 February 2026, **Competition closes:** Wednesday 15 April 2026 11:00am

The UKRI logo consists of the letters 'UK' stacked above 'RI' in a bold, white, sans-serif font, set against a dark purple square background.

Innovate
UK

Thank You –
...add onward to Q & A...